


PATENT NUMBER

U.S. UTILITY PATENT APPLICATION

O.I.P.E. m7k SCANNED <u>SB2</u> Q.A. <u>L</u>	PATENT DATE
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APPLICATION NO. 09/380312	CONT/PRIOR D F	CLASS 257	SUBCLASS C 07	ART UNIT -2811	EXAMINER 
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APPLICANTS

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TITLE

Resin molded type semiconductor device 100 100

manufacturing the same 100 100

PTO-2040
12/89

PREPARED AND APPROVED FOR ISSUE

[illegible]

<input type="checkbox"/> TERMINAL DISCLAIMER	DRAWINGS <div> <div>Sheets Dwrg.</div> <div>Figs. Dwrg.</div> <div>Print Fig.</div> </div>		CLAIMS ALLOWED	
			Total Claims	Print Claim for O.G.
<input type="checkbox"/> a) The term of this patent subsequent to _____ (date) has been disclaimed.	_____ (Assistant Examiner) (Date)		NOTICE OF ALLOWANCE MAILED	

			ISSUE FEE	
<input type="checkbox"/> b) The term of this patent shall not extend beyond the expiration date of U.S. Patent. No. _____ _____ _____	_____ (Primary Examiner) (Date)		Amount Due	Date Paid

<input type="checkbox"/> c) The terminal _____ months of this patent have been disclaimed.	_____ (Legal Instruments Examiner) (Date)		ISSUE BATCH NUMBER	

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